



# Technology development for nano-pillars fabrication in silicon carbide to enhance light collection from color centers

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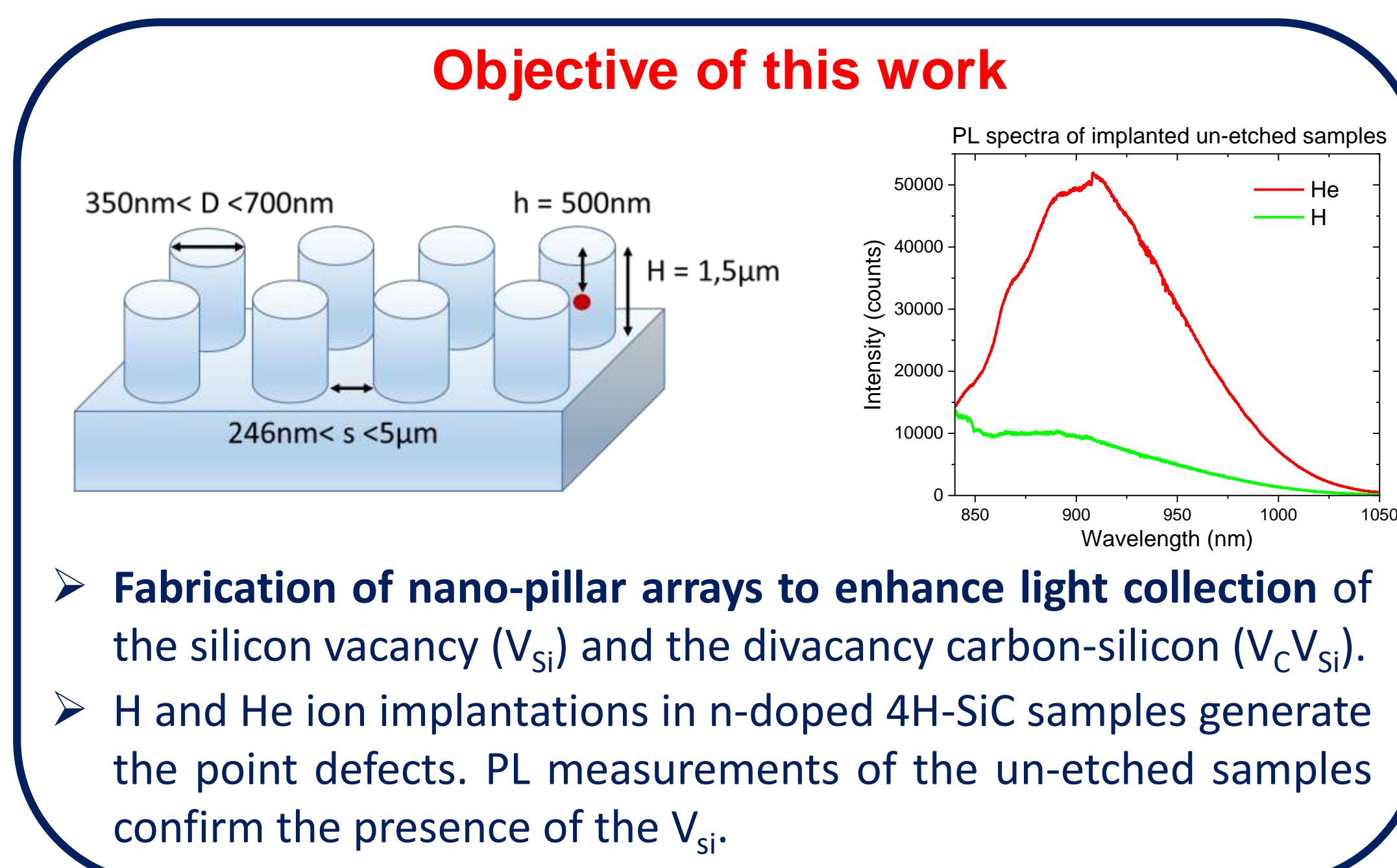
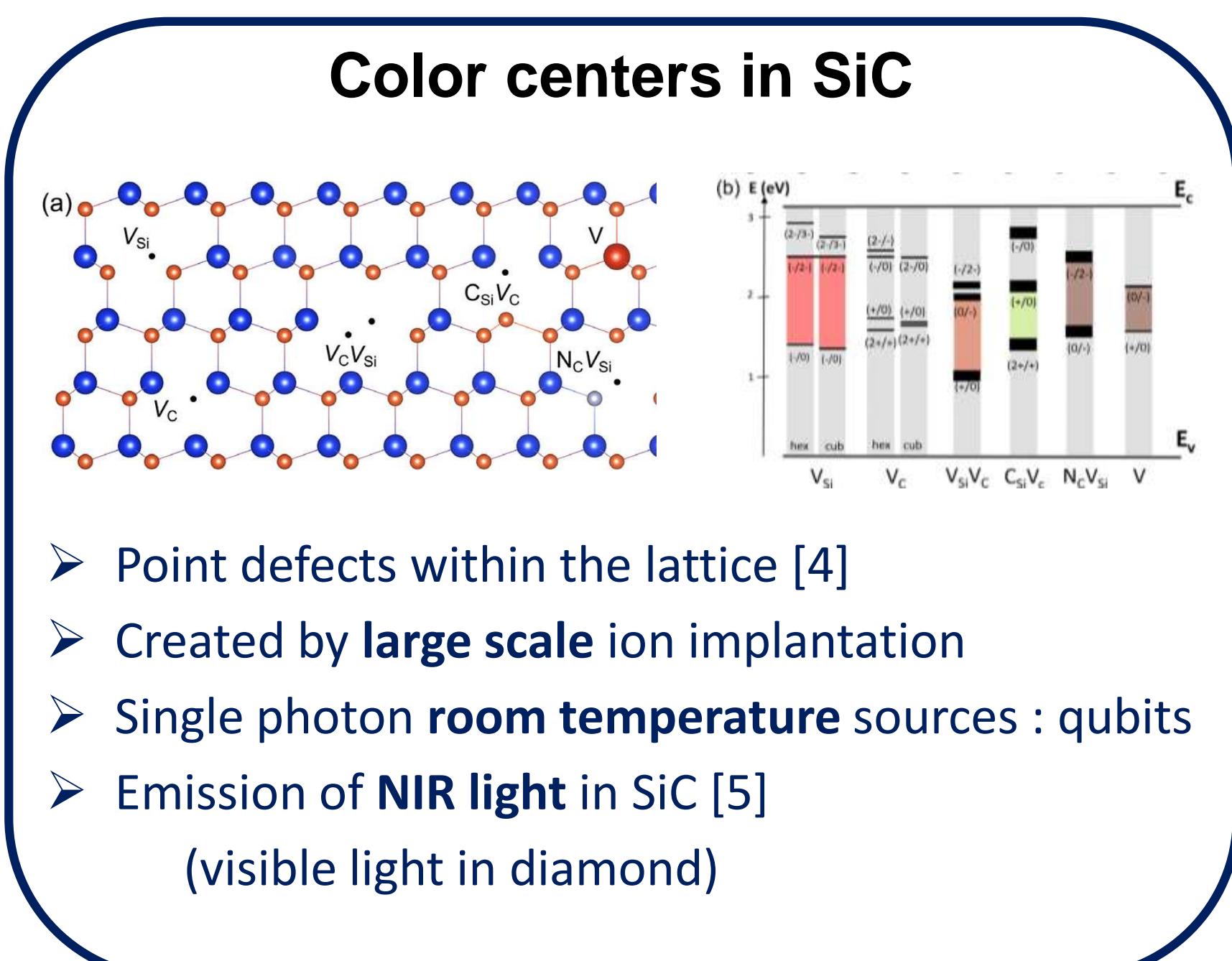
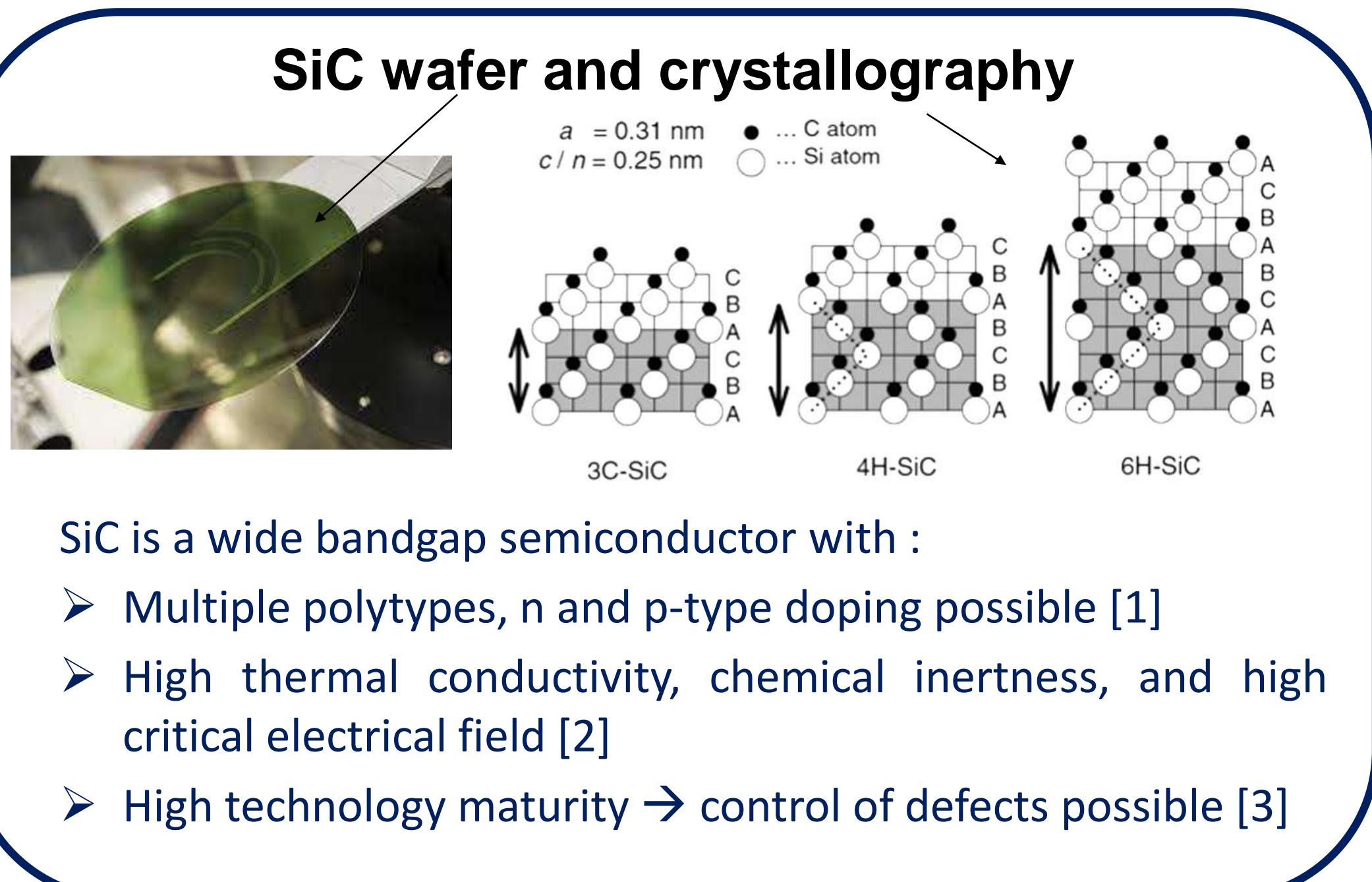
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# Technology development for nano-pillars fabrication in silicon carbide to enhance light collection from color centers

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## Context and objectives



## Methods

### E-beam lithography

- Surface cleaning with HF
- Pre-bake of the samples at 170°C for 20min
- PMMA resist 4,5g/L**  
40s, 2500rpm, 1000rpm/s
- Baking of the resist at 170°C for 30min  
Resist thickness : 450nm
- E-beam lithography**
  - Gun 20kV
  - Aperture diameter 30μm
  - Dose 1,45
  - Current 345pA



### E-beam Physical Vapor Deposition

- Development**
  - 1min20s in MIBK/IPA
  - 15s in IPA
- Cr-mask deposition**
  - 75nm 0,1nm/s, 30mA (x2)
  - Vacuum < 1,10<sup>-5</sup>mbar
- Lift-off**
  - 1<sup>st</sup> immersion few minutes in acetone
  - 2<sup>nd</sup> immersion for two days
  - Acetone spraying to remove last pieces of metal
  - 20s in IPA



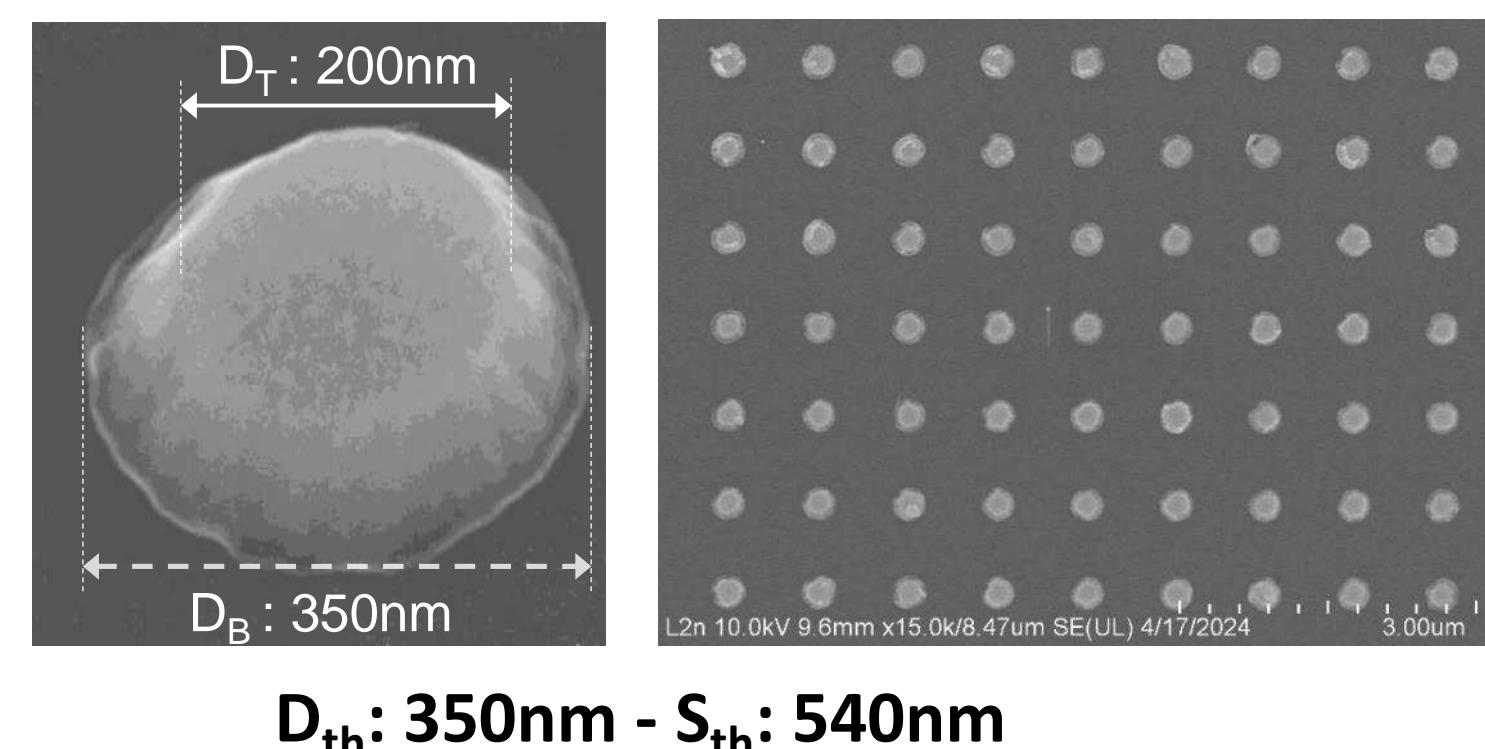
### RIE/ICP plasma etching

- Deposition of a 100nm-thick Si layer
  - Nano-pillars etching**
    - SF<sub>6</sub>/O<sub>2</sub> : 10/2sccm, 8mbar pressure
    - RIE/ICP power : 100/1000W for 5min
    - Bias : -260V
  - Cr-mask removing** : 2 days in a Cr-etchant
- Arrays of SiC pillars obtained with different diameters (D) and spacings (s)



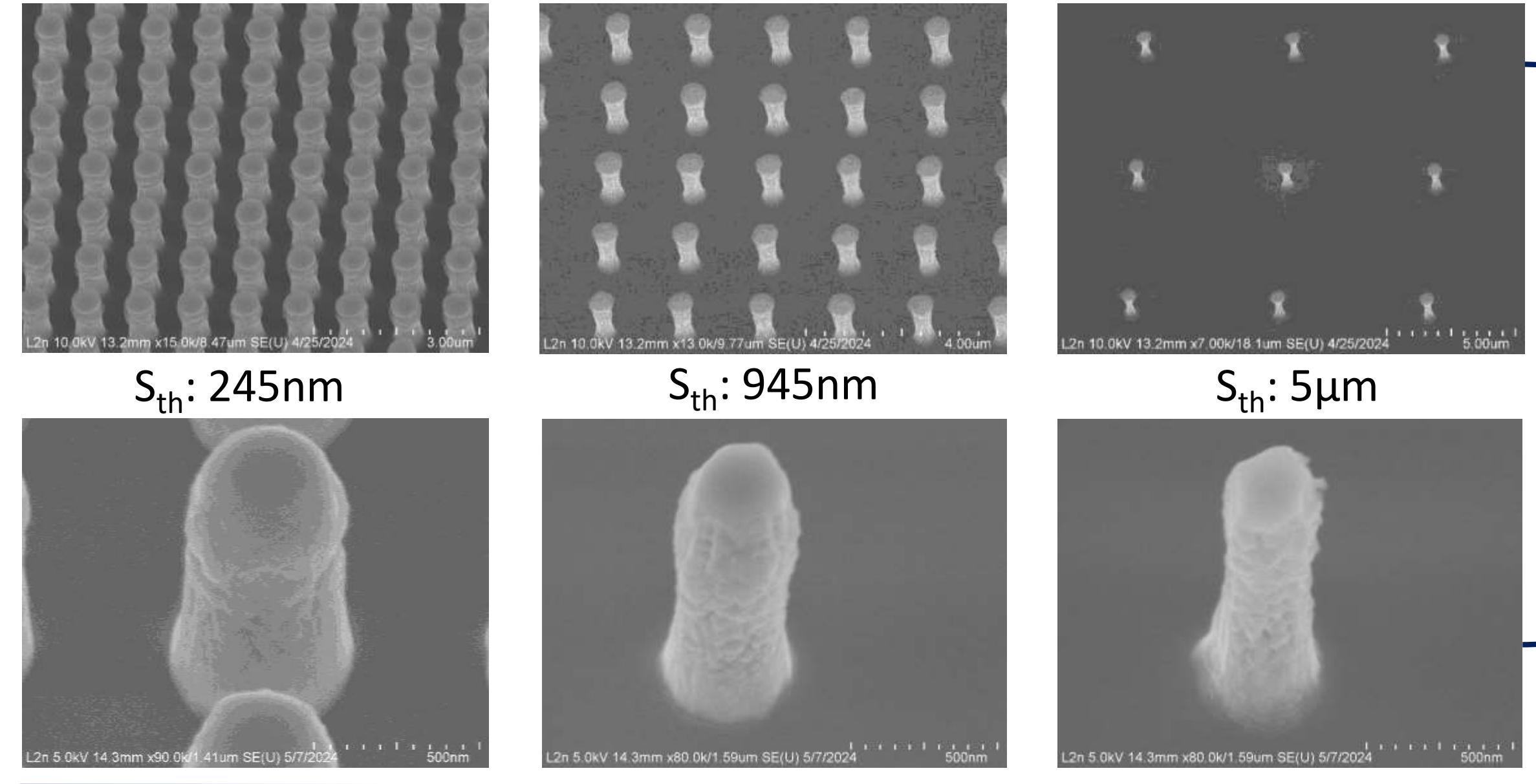
## Results and Discussion

### Cr-masks



- Conic geometry of the mask
- Bottom of the mask has the diameter wanted ( $D_B = D_{th}$ )
- Top of the mask is about 150nm less large than the bottom
- Lead to etched nano-pillars at least 150nm thinner than wanted

### Nano-pillars



$D_{th}: 700\text{nm}$

$S_{th}: 940\text{nm}$

## Conclusion

- Nano-pillars arrays** with different diameters and spacings were fabricated. Pillars have a height of 1,4μm with no trenching.
- Conic aspect of the Cr-mask** : heating and deformation of the PMMA resist during deposition ?  $D_{th}$  should be increased of about 150nm to compensate.
- Lateral etching** of the pillars : different etching parameters will be used to reduce this phenomenon. We can also increase  $D_{th}$  if lateral etching is repeatable.
- Next experiments will be done in **implanted samples** and PL spectra will be measured.

## References

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- **Lateral etching** of the nano-pillars : ↗ when the spacing ↗. When  $D_{th}$  ↗, lateral etching ↘ slightly.
- No trenching is observed. Pillars height is 1,4μm.
- Nano-pillars of smaller dimensions fell and non-linearity of lateral etching with D or S..